


## Full Material Declaration for attached parts list

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	<p><b>Diotec Semiconductor AG</b>  <b>DUNS-Nummer:</b> 330866844          -, Kreuzmattenstr. 4, Heitersheim, B.-W., 79423, Germany  <b>Declarations Autorisiert durch:</b>          Udo Steinebrunner, Product Manager, -</p>
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## Materialien und Stoffe

Verwendung/Andordnung	Material group	% w/w des Materials im Artikel	Substances in the material	CAS Number	% w/w des Stoffs im Artikel
Chip (die)	Other inorganic materials	0.50000%	Silicon dioxide	14808-60-7	1.00000%
			Gold	7440-57-5	11.50000%
			Polydimethylsiloxane rubber	63394-02-5	25.00000%
			Silicon	7440-21-3	62.50000%
			Silver	7440-22-4	2.50000%
Die attach	Lead and Lead alloys	0.20000%	Tin	7440-31-5	5.00000%
			Lead	7439-92-1	92.50000%
Encapsulation	EP (Epoxy resin)	33.00000%	1,3-Isobenzofurandione, hexahydro-5-methyl-	19438-60-9	0.10000%
			Low molecular weight solid DGEBA- based epoxy resins	25068-38-6	1.25000%
			Benzyl-N,N-dimethylamine	103-83-3	3.10000%
			1,3- Isobenzofurandione, 3a,4,7,7a- tetrahydro- 4-methyl-	5333-84-6	6.00000%
			cis-1,2,3,6-Tetrahydrophthalic anhydride	85-43-8	9.25000%
			1,3-Isobenzofurandione, tetrahydro-5-methyl-	34090-76-1	10.65000%
			7-Oxabicyclo(4.1.0)heptane-3- carboxylic acid, 7-oxabicyclo(4.1.0)hept- 3-ylmethyl ester	2386-87-0	14.65000%
Silica	14808-60-7	55.00000%			

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Housing	UP (Unsaturated polyester)	26.00000%	ANTIMONY TRIOXIDE	1309-64-4	17.00000%
			polyethylene-ethyl acrylate	9010-86-0	28.00000%
			Glass fibers	65997-17-3	55.00000%
Leadfinish	Tin plating	0.10000%	Tin	7440-31-5	100.00000%
Leadframe	Copper (e.g. copper amounts in cable harnesses)	40.20000%	Copper	7440-50-8	100.00000%

**Beigefügte Artikelliste**

Part number	Artikelbezeichnung	Artikelmasse	Artikelmasse UoM
PB10xx	Bridge Rectifier Square	3.5	g